



YEA SHIN TECHNOLOGY CO., LTD

YS3810HCB

# Dual N-Channel Enhancement MOSFET

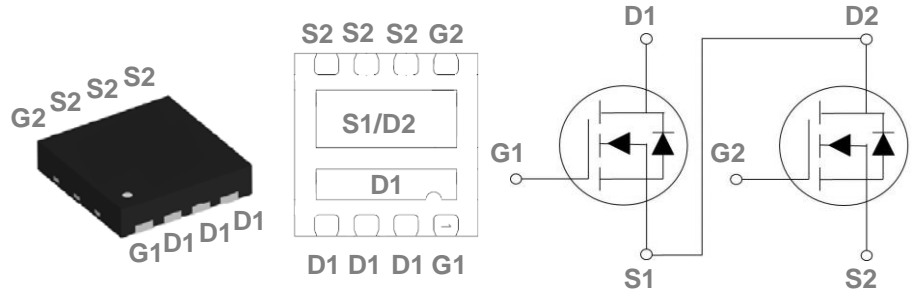


VDS= 30V, ID= 19.5A

## Features

- Improved  $dv/dt$  capability
- Fast switching
- 100% EAS Guaranteed
- Halogen free

## DFN3x3 Asymmetric Dual Pin Configuration



## Applications

- MB / VGA / Vcore
- POL Buck Applications
- SMPS 2<sup>nd</sup> SR

## Absolute Maximum Rating $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	19.5	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	12.3	A
	Drain Current – Continuous ( $T_A=25^\circ\text{C}$ )	10.8	A
	Drain Current – Continuous ( $T_A=100^\circ\text{C}$ )	6.8	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	78	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	13	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	16	A
P <sub>D</sub>	Power Dissipation ( $T_A=25^\circ\text{C}$ )	27	W
	Power Dissipation – Derate above 25°C	0.01	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	4.6	°C/W

# DEVICE CHARACTERISTICS

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Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.04	---	$V/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=30V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=24V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA

### On Characteristics

$R_{DS(ON)}$	Static Drain-source On-Resistance <sup>3</sup>	$V_{GS}=10V, I_D=10A$	---	8.5	10.5	$m\Omega$
		$V_{GS}=4.5V, I_D=5A$	---	11	14	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-4	---	$mV/^\circ\text{C}$
$g_{fs}$	Forward Transconductance	$V_{DS}=5V, I_D=5A$	---	12	---	S

### Dynamic and Switching Characteristics

$Q_g$	Total Gate Charge <sup>3,4</sup>	$V_{DS}=15V, V_{GS}=10V, I_D=5A$	---	15.6	31	nC
$Q_{gs}$	Gate-Source Charge <sup>3,4</sup>		---	2.3	5	
$Q_{gd}$	Gate-Drain Charge <sup>3,4</sup>		---	3	6	
$T_{d(on)}$	Turn-On Delay Time <sup>3,4</sup>	$V_{DD}=15V, V_{GS}=10V, R_G=6\Omega, I_D=1A$	---	3.8	7	ns
$T_r$	Rise Time <sup>3,4</sup>		---	10	19	
$T_{d(off)}$	Turn-Off Delay Time <sup>3,4</sup>		---	22	42	
$T_f$	Fall Time <sup>3,4</sup>		---	6.6	13	
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1\text{MHz}$	---	620	900	pF
$C_{oss}$	Output Capacitance		---	85	125	
$C_{rss}$	Reverse Transfer Capacitance		---	60	90	
$R_g$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, f=1\text{MHz}$	---	2.8	5.6	$\Omega$

### Drain-Source Diode Characteristics and Maximum Ratings

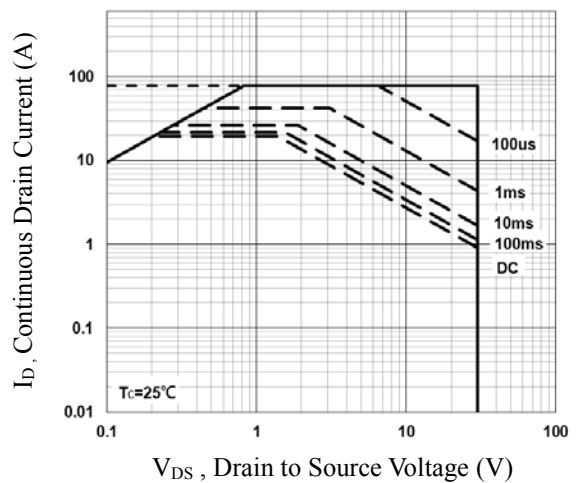
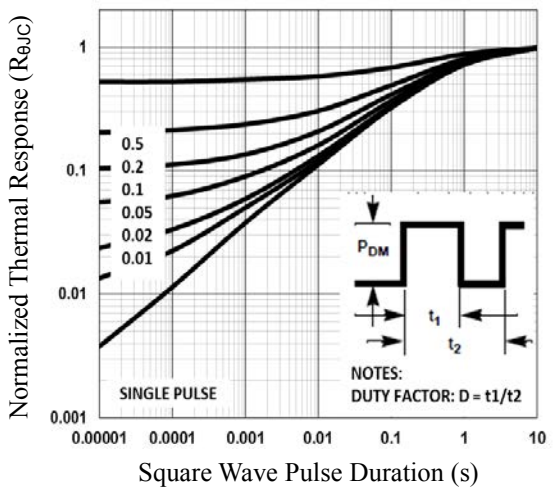
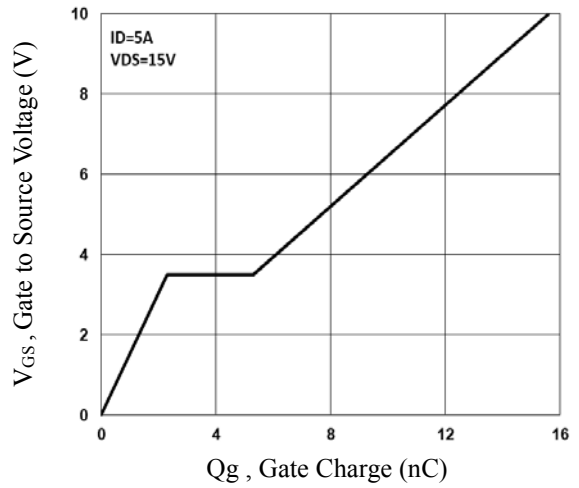
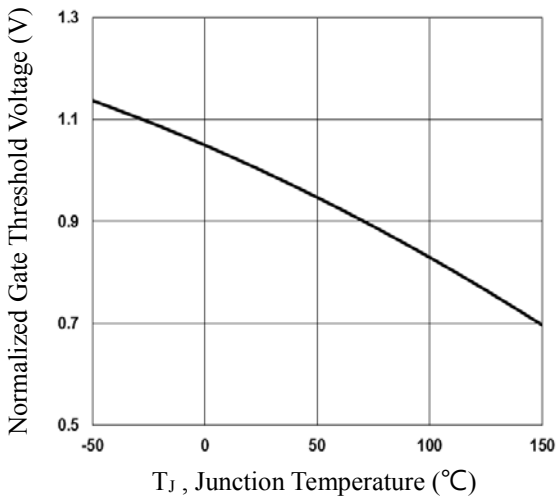
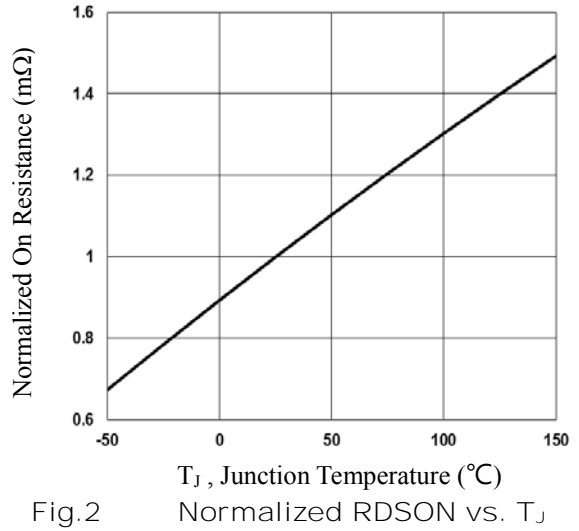
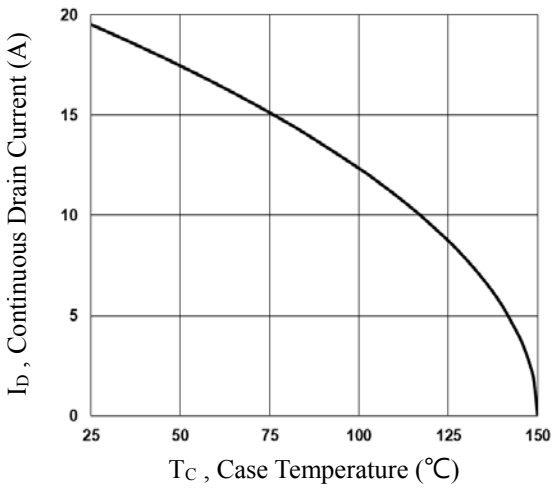
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	19.5	A
$I_{SM}$	Pulsed Source Current <sup>3</sup>		---	---	39	A
$V_{SD}$	Diode Forward Voltage <sup>3</sup>	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, Q1:I_{AS}=16A, Q2:I_{AS}=42A, R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

# DEVICE CHARACTERISTICS

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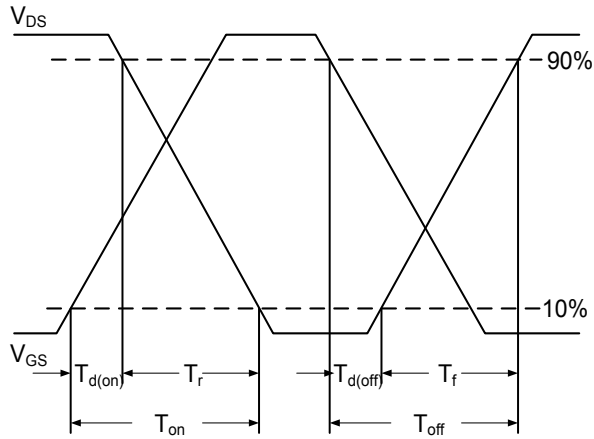


Fig.7 Switching Time Waveform

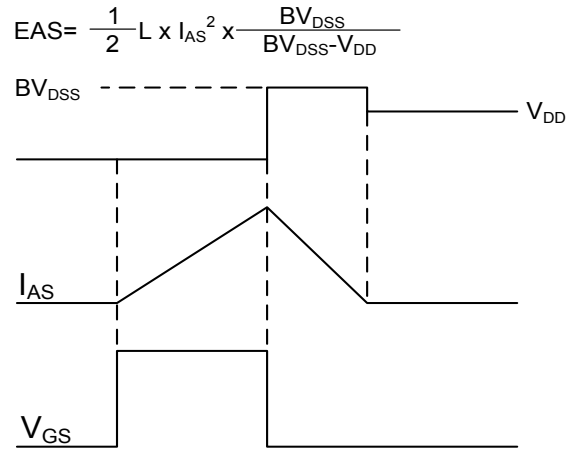
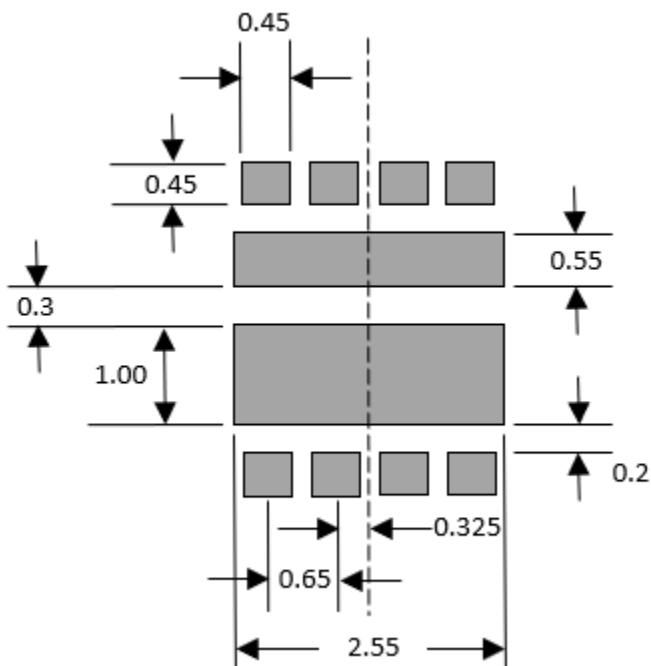


Fig.8 EAS Waveform

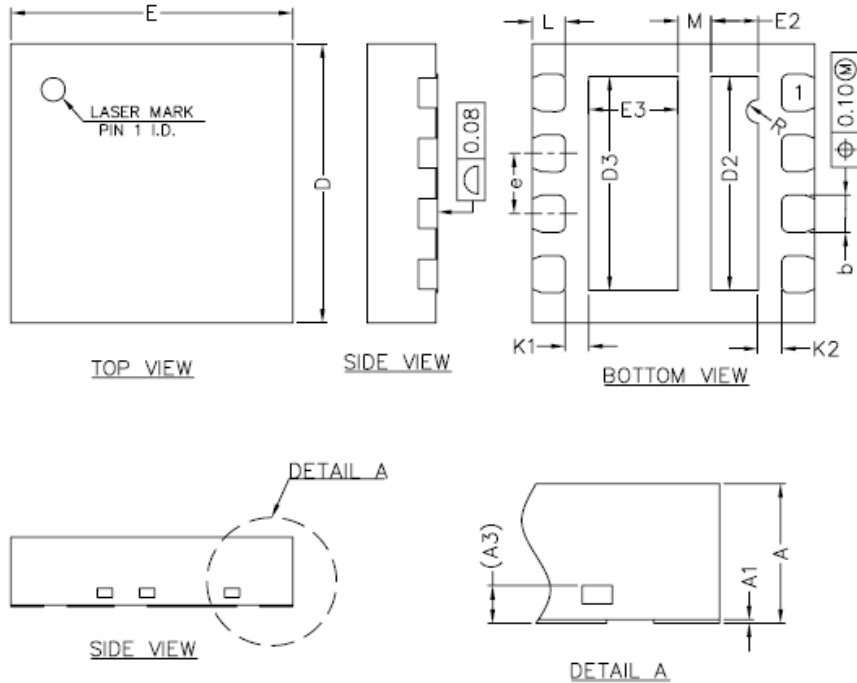
## RECOMMEND FOOTPRINT Information



# PACKAGE OUTLINE & DIMENSIONS

## YS3810HCB

### DFN3x3 Asymmetric Dual Package Information



Symbol	Dimensions In Millimeters		
	Min	Typ	Max
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	0.20REF		
b	0.35	0.40	0.45
D	2.90	3.00	3.10
E	2.90	3.00	3.10
D2	2.20	2.30	2.40
E2	0.40	0.50	0.60
D3	2.20	2.30	2.40
E3	0.85	0.95	1.05
e	0.55	0.65	0.75
K1	0.15	0.25	0.35
K2	0.15	0.25	0.35
L	0.30	0.35	0.40
M	0.25	0.35	0.45
R	0.125REF		